

#### **Applications**

- IEEE802.11b DSSS WLAN
- IEEE802.11g,n OFDM WLAN
- Embedded applications

#### Features

- □ Integrates SP3T Switch and LNA with by-pass mode
- □ 12 dB gain,
- □ 1.8 dB NF
- 0.7 dB Bluetooth path loss
- □ 2x2x 0.6mm, QFN Package, MSL 1
- Lead free, Halogen free and RoHS compliant

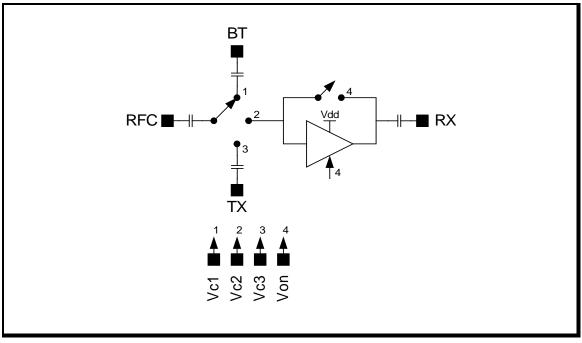
### **Ordering Information**

| Part No.    | Package | Remark         |
|-------------|---------|----------------|
| SE2601T     | QFN     | Samples        |
| SE2601T-R   | QFN     | Tape and Reel  |
| SE2601T-EK1 | N/A     | Evaluation kit |

# **Functional Block Diagram**

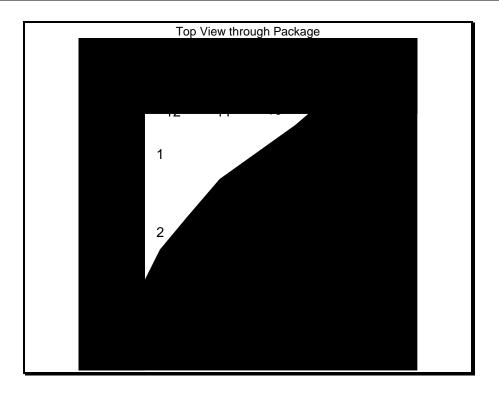
### Product Description

The SE2601T is a single chip integrated front-end with a Bluetooth port to complement WLAN chipsets with integrated Power Amplifier. The Front-end integrates SP3T Switch and Low Noise Amplifier with bypass mode in an ultra compact package. It is capable of switching between WLAN RX, WLAN TX and Bluetooth<sup>™</sup>









# **Pin Out Description**

| Pad | Label | _abel Function                |  |  |
|-----|-------|-------------------------------|--|--|
| 1   | GND   | Ground                        |  |  |
| 2   | GND   | Ground                        |  |  |
| 3   | Von   | LNA control pin               |  |  |
| 4   | RX    | WLAN Receive port             |  |  |
| 5   | VDD   | Positive power supply voltage |  |  |
| 6   | Vc2   | RX switch control pin         |  |  |
| 7   | GND   | Ground                        |  |  |
| 8   | BT    | Bluetooth port                |  |  |
| 9   | Vc1   | BT switch control pin         |  |  |
| 10  | RFC   | RF Common (antenna port)      |  |  |
| 11  | VC3   | TX switch control pin         |  |  |
| 12  | ТΧ    | WLAN Transmit port            |  |  |



### **Absolute Maximum Ratings**

These are stress ratings only. Exposure to stresses beyond these maximum ratings may cause permanent damage to, or affect the reliability of the device. Avoid operating the device outside the recommended operating conditions defined below. This device is ESD sensitive. Handling and assembly of this device should be at ESD protected workstations.

| Symbol             | Definition   | Min. | Max.    | Unit |
|--------------------|--|------|---------|------|
| Vdd                | Supply Voltage on Vdd                              | 0    | 3.6     | V    |
| Von, cc            | DC input on control pins                           | -0.5 | Vdd+0.5 | V    |
| P <sub>TXIN</sub>  | TX Input Power, ANT terminated in $50\Omega$ match | -    | 27      | dBm  |
| TA                 | Operating Temperature Range                        | -40  | 85      | °C   |
| Тѕтс               | Storage Temperature Range                          | -40  | 150     | °C   |
| ESD <sub>HBM</sub> | JEDEC JESD22-A114<br>all pins                      | 1000 |         | V    |

### **Recommended Operating Conditions**

| Symbol  | Parameter                               | Min. | Тур. | Max. | Unit |
|---------|---|------|------|------|------|
| TA      | Ambient temperature                     | -40  | 25   | 85   | °C   |
| Vdd     | Supply voltage, relative to $GND = 0 V$ | 2.7  | 3.3  | 3.6  | V    |
| Von, cc | Control voltage, relative to GND = 0 V  | 0    | -    | Vdd  | V    |

# **DC Electrical Characteristics**

Conditions: V<sub>dd</sub> = 3.3 V, T<sub>A</sub> = 25 °C, as measured on Skyworks SE2601T EK1 evaluation board (de-embedded to device), all unused ports terminated with 50 ohms, unless otherwise noted

| Symbol | Parameter                  | Conditions  | Min. | Тур. | Max. | Unit |
|--------|----------------------------|-------------|------|------|------|------|
| ldd    | LNA current                | Gain mode   | -    | 10   | 13   | mA   |
| ldd    | LNA current                | Bypass mode |      |      | 60   | μA   |
| Ιον    | LNA control current        |             | -    |      | 20   | uA   |
| Ic1    | BT port control<br>current |             | -    |      | 20   | μA   |
| lc3    | TX port control<br>current |             | -    |      | 20   | μA   |
| VIH    | Logic input high           |             | 2.7  |      | 3.6  | V    |
| VIL    | Logic input low            |             | 0    |      | 0.3  | V    |



### **Control Logic Table**

| Mode# | Mode Description | Vc1 | Vc2 | Vc3 | Von |
|-------|------------------|-----|-----|-----|-----|
| 0     | All Off          | 0   | 0   | 0   | 0   |
| 1     | Тх               | 0   | 0   | 1   | 0   |
| 2     | BT               | 1   | 0   | 0   | 0   |
| 3     | Rx – high gain   | 0   | 1   | 0   | 1   |
| 4     | Rx - bypass      | 0   | 1   | 0   | 0   |

### **AC Electrical Characteristics**

#### Transmit Characteristics (RFC-TX port)

Conditions: V<sub>dd</sub> = 3.3 V, T<sub>A</sub> = 25 °C, as measured on Skyworks Solutions' SE2601T EK1 evaluation board (deembedded to device), all unused ports terminated with 50 ohms, unless otherwise noted. Vc1 = Vc2 = Von = 0.

| Symbol             | Parameter          | Condition | Min. | Тур. | Max. | Unit |
|--------------------|--------------------|-----------|------|------|------|------|
| Fout               | Frequency Range    | -         | 2400 | -    | 2500 | MHz  |
| TXı∟               | Insertion Loss     |           | -    | 0.7  | 0.9  | dB   |
| S <sub>11</sub>    | Input Return Loss  |           |      | -16  | -13  | dB   |
| S <sub>22</sub>    | Output Return Loss |           |      | -16  | -13  | dB   |
| ISOL <sub>SW</sub> | Switch Isolation   | Vc3 = 0   | 23   |      |      | dB   |
| IP1dB              | Input P1dB         |           | 31   |      |      | dBm  |

#### **Bluetooth Characteristics (RFC-BT port)**

Conditions: V<sub>dd</sub> = 3.3 V, T<sub>A</sub> = 25 °C, as measured on Skyworks Solutions' SE2601T EK1 evaluation board (deembedded to device), all unused ports terminated with 50 ohms, unless otherwise noted. Vc2 = Vc3 = Von = 0.

| Symbol             | Parameter           | Condition | Min. | Тур. | Max. | Unit |
|--------------------|---------------------|-----------|------|------|------|------|
| Fout               | Frequency Range     | -         | 2400 | -    | 2500 | MHz  |
| BTı∟               | Insertion Loss      |           | -    | 0.7  | 0.9  | dB   |
| S <sub>11</sub>    | BT Port Return Loss |           |      | -16  | -14  | dB   |
| S <sub>22</sub>    | BT Port Return Loss |           |      | -16  | -14  | dB   |
| IP1dB              | Input P1dB          |           | 31   |      |      | dBm  |
| ISOL <sub>SW</sub> | Switch Isolation    | Vc1 = 0   | 25   |      |      | dB   |



### **Receive Characteristics (RF- RX port)**

|             | , ,                           | unused ports terminated with |      |      |      | ,    |
|-------------|-------------------------------|------------------------------|------|------|------|------|
| Symbol      | Parameter                     | Condition                    | Min. | Тур. | Max. | Unit |
| Fout        | Frequency Range               | -                            | 2400 | -    | 2500 | MHz  |
| <b>S</b> 21 | Receive Gain, LNA enabled.    |                              | 11   | 12   | 13   | dB   |
| NF          | Noise Figure                  |                              | -    | 1.8  | 2.0  | dB   |
| <b>S</b> 11 | Input Return Loss             |                              |      | -10  | -8   | dB   |
| <b>S</b> 22 | Output Return Loss            |                              |      | -10  | -8   | dB   |
| IP1dB       | Input P1dB                    |                              | -7   | -6   |      | dBm  |
| S21-BYP     | Receive Gain, LNA<br>bypassed |                              | -4   | -3   |      | dB   |

Conditions: V<sub>dd</sub> = 3.3 V, T<sub>A</sub> = 25 °C, as measured on Skyworks Solutions' SE2601T EK1 evaluation board (de-



#### **Package Handling Information**

### **Branding Information**

The device branding is shown in Figure 4.

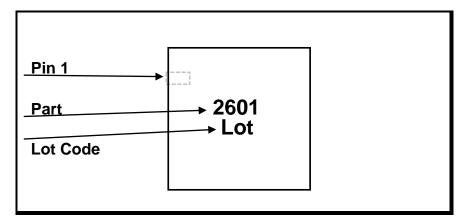


Figure 4: SE2601T Branding and Pin 1 Location

#### Package Diagram

The package diagram is shown in Figure 5.

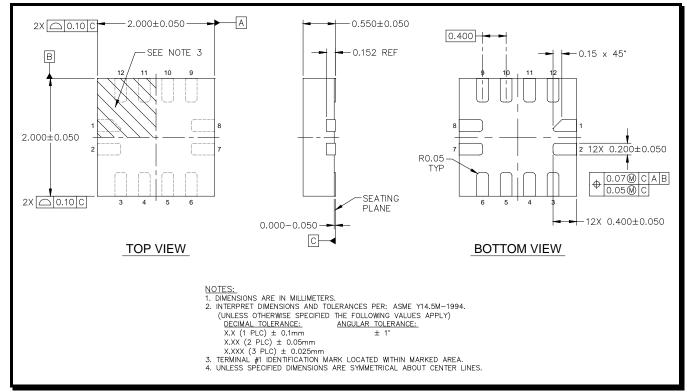
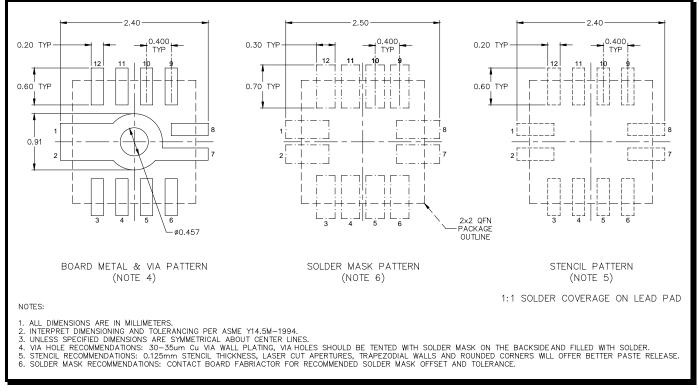


Figure 5: SE2601T Package Diagram





# **Recommended PCB Footprint Recommendations**

Figure 6: SE2601T PCB Footprint Recommendations

# Package Handling Information

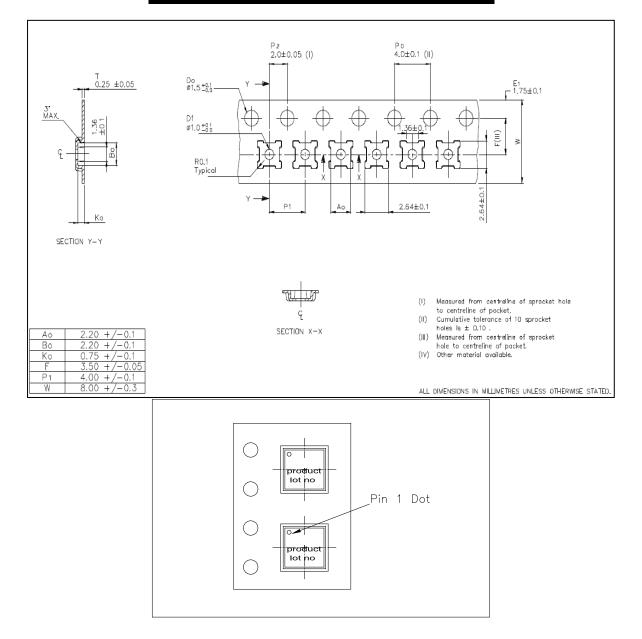
Because of its sensitivity to moisture absorption, instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly. The SE2601T is capable of withstanding a Pb free solder reflow. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is manually attached, precaution should be taken to insure that the device is not subjected to temperatures above its rated peak temperature for an extended period of time. For details on both attachment techniques, precautions, and handling procedures recommended, please refer to:

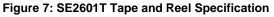
- "QFN solder reflow and rework information application note", Document Number QAD-00045
- "Handling, packing, shipping and use of moisture sensitive QFN application note", Document Number QAD-00044



# Tape and Reel Specification

| Parameter        | Value         |
|------------------|---------------|
| Devices Per Reel | 3000          |
| Reel Diameter    | 7 inches      |
| Tape Width       | 8 millimeters |







#### **Document Change History**

| Revision | Date            | Notes  |
|----------|-----------------|--|
| 1.0      | 09/08/2009      | Created  |
| 1.1      | 09/10/2009      | Corrected package height on page 1   |
| 1.2      | 12/18/2009      | Updated ESD specification, Package Outline and added recommended PCB footprint |
| 1.3      | Jan-06-2010     | Updated ESD specification and corrected typo                                   |
| 1.4      | March-01-2010   | Added Tape and reel specification  |
| 1.5      | June-10-2010    | Updated tape and reel information  |
| 1.6      | August-02-2010  | Updated ESD specification  |
| 1.7      | January-23-2011 | Updated BT IP1dB and VIH specification   |
| 1.8      | April-10-2012   | Updated with Skyworks logo and disclaimer statement                            |

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